IPC - ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This leve	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1					Form Type * Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and Mfg Information				
upplier Inform	ation														
Company name*			Company unique ID			Ur	Unique ID Authority					Response Date*			
onsemi											2024-05-19				
Contact Name			Title - Contact			Ph	Phone - Contact*				Email - Contact*				
Product-Env-Stewards			Product Enviro Compliance			N	NA				Product-Env-Stewards@onsemi.com				
uthorized Represe	ntative*	,	Title - Representative			Ph	Phone - Representative*			Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance			N	NA				Product-Env-Stewards@onsemi.com				
Requeste	r Item Number	Mfr Item N	Number Mfr Item Name				Effective Date	Version	M	Ianufacturing Site	W	eight*	UOM	Unit Type	
	LE25S161PCTXG 16M bit serial fla USON8		16M bit serial flash t USON8	memory, Vcc=1.8	3V, 2	024-05-19	5-19 CNH		2:	5.56	mg	Each			
Ianufacturing	Process Information	n													
Terminal l	Plating / Grid Array Mater	ial Ter	rminal Base	Alloy J-S	TD-020 MSL Rat	ting	Peak Proce	ss Body Tem	perature	e Max Time at Peak	Temperatu	re Numb	er of Reflow Cyc	eles	
Matte Tin (Sn) - annealed		CU	CU Alloy 2				260	C 30		second	s 3				
omments															
TTENTION: MSL	2 Rated item requires D	ry Pack (aft	ter electrical	l test)											
or more informatio	on regarding material cor	nposition pl	lease refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of						
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.369	mg	Supplier	Silicon (Si)	7440-21-3		1.369	mg
Die Attach	0.187	mg		Epoxy resin	proprietary data		0.0374	mg
			Supplier	Hardener	Proprietary Data		0.0037	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.0187	mg
			Supplier	Other Additive Agents	Proprietary Data		0.015	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.1122	mg
Lead Frame	13.538	mg	Supplier	Silver (Ag)	7440-22-4		0.3425	mg
			Supplier	Magnesium (Mg)	7439-95-4		0.0203	mg
			Supplier	Silicon (Si)	7440-21-3		0.0853	mg
			В	Nickel (Ni)	7440-02-0		0.3953	mg
			Supplier	Copper (Cu)	7440-50-8		12.6946	mg
Mold Compound-Black	9.648	mg		Epoxy resin	proprietary data		0.4824	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0482	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		8.635	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.4824	mg
Plating	0.342	mg	Supplier	Tin (Sn)	7440-31-5		0.342	mg
Wire Bond - Au	0.476	mg	Supplier	Gold (Au)	7440-57-5		0.476	mg